

### Abstract of the Disclosure

~~A method~~ 3-D structures utilizing which are fabricated by gray-tone exposure of a class of thick negative photo-sensitized epoxy resists from the substrate side of a transparent substrate, using ~~and~~ development methods that rely upon a physical distinction between polymerized (solid) and unpolymerized (liquid) photoresist at elevated temperatures ~~may be used to fabricate 3-D structures in the photo-sensitized epoxy.~~ Such structures may exhibit smoothly-varying topographic features with thicknesses as great as 2 mm.